

46-3492 Economy Version

SMT-Buchsenleisten RM 2,54mm, stehend – BH 3,71mm, beidseitig steckbar
SMT Female Headers, 2.54mm Pitch, Vertical – 3.71mm Profile, Dual Entry

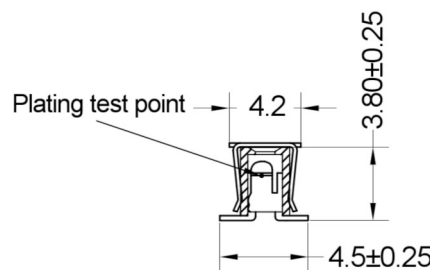
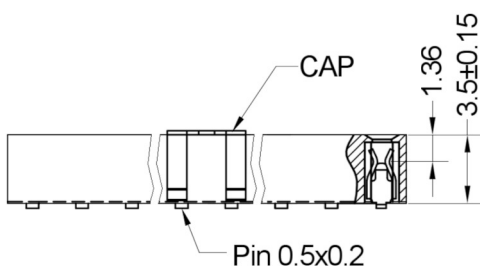
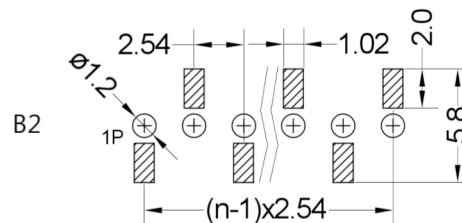
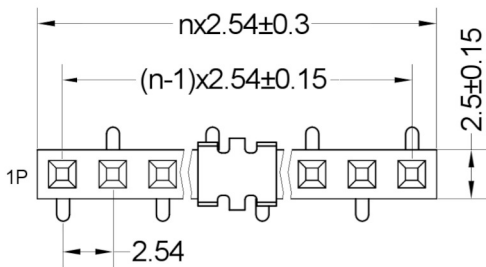
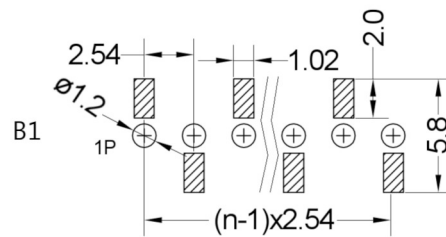
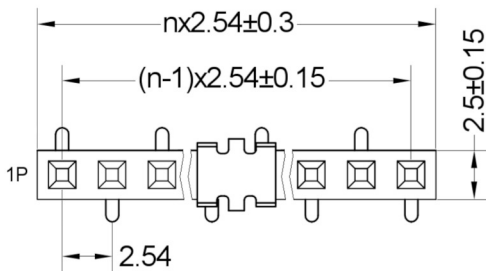
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Kupferlegierung <i>Copper alloy</i>
Kontaktoberfläche <i>Contact Surface</i>	Au über Ni <i>Au over Ni</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ < 20 mΩ
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ > 1000 MΩ
Spannungsfestigkeit <i>Test Voltage</i>	1000 V AC/DC 1000 V AC/DC
Nennstrom <i>Current Rating</i>	3 A 3 A
Temperaturbereich <i>Temperature Range</i>	-40 °C ... +105 °C -40 °C ... +105 °C
Verarbeitung <i>Processing</i>	230 °C für 30-60 Sekunden (260 °C für 10 Sekunden) 230 °C for 30-60 seconds (260 °C for 10 seconds)



Doppelfederkontakte für
Vierkantstifte 0,635mm.
Dual beam contacts accept
0.635mm square pins.

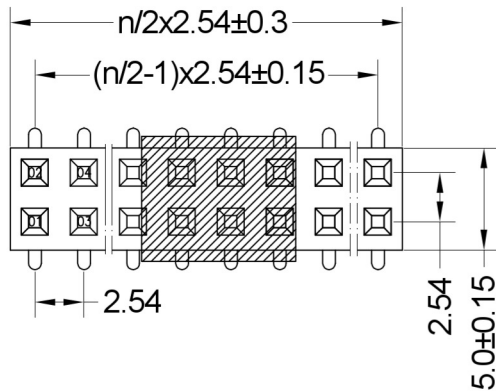
Recommended PCB Layout (Top Side) (PCB BOARD TOLERANCE ±0.05)



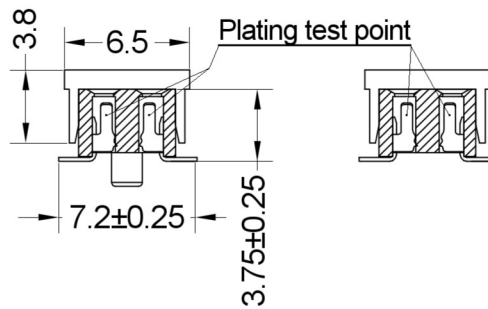
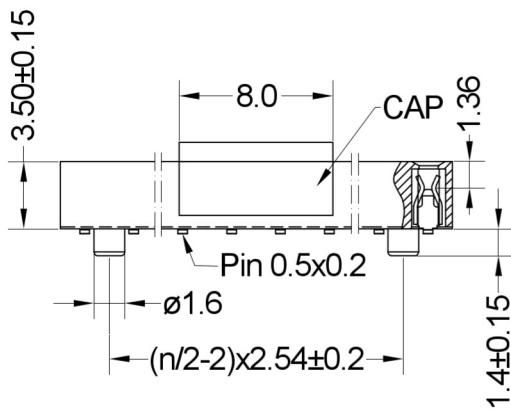
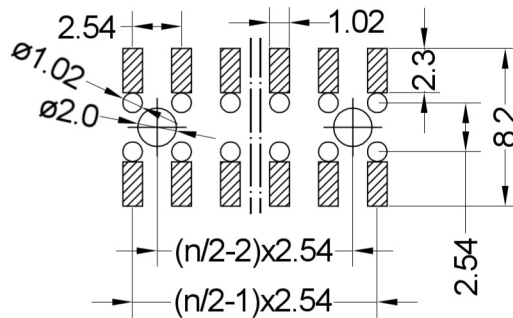
Series	Contacts*	Rows*	Plating	Locating Pegs*	Packaging*
46-3492	40 02-40 Einreihig Single row	1 1 Einreihig B1 Single row B1 2 Einreihig B2 Single row B2	00 00 Vergoldet Gold plated	00 00 Ohne Pos.hilfen W/o loc. pegs	ST ST MPST MPTR

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Recommended PCB Layout (Top Side)
 (PCB BOARD TOLERANCE ±0.05)



Series	Contacts*	Rows	Plating	Locating Pegs*	Packaging*
46-3492	40 04-80 Zweireihig Double row	3 3 Zweireihig Double row	00 00 Vergoldet Gold plated	00 00 Ohne Pos.hilfen W/o loc. pegs 10 Mit Pos.hilfen With loc. pegs	ST ST PPST PPTR

Lieferformen / Packaging Options:

- ST** In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads
- MPST** In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads
- MPTR** Tape & Reel mit Pick&Place-Pads / Tape & Reel with Pick&Place-Pads
- ST** In Stangen ohne Pick&Place-Pads / In tubes w/o Pick&Place-Pads
- PPST** In Stangen mit Pick&Place-Pads / In tubes with Pick&Place-Pads
- PPTR** Tape & Reel mit Pick&Place-Pads / Tape & Reel with Pick&Place-Pads

* Dies ist ein **Bestellbeispiel** - bitte durch Ihre Spezifikationen ersetzen.
 * This is an **order example** - please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	untere Temperaturangabe [°C]
Verweildauer oberhalb T_L	laut Angabe im Datenblatt [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	obere Temperaturangabe [°C]
Dauer Höchsttemperatur	laut Angabe im Datenblatt [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	Lower Temperature [°C]
Duration above T_L	Acc. to datasheet [sec]
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	Upper Temperature [°C]
Duration Peak Temperature	Acc. to datasheet [sec]
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

